

Program Overview

THURSDAY 15 September

	MAP (Conference Room A)	RTS (Exhibition Hall)
10:00 ~ 13:00	Reception & Registration	Reverse Trade Show
13:00 ~ 13:15 13:15 ~ 14:45	Opening Remark SESSION 1 : Invited Talks	
14:45 ~ 15:00	COFFEE BREAK	Reverse Trade Show
15:00 ~ 15:40	SESSION 2 : JEITA Program	
15:40 ~ 16:00	COFFEE BREAK	Reverse Trade Show
16:00 ~ 17:30	SESSION 3 : Package-on-Package Technology	
17:30 ~ 17:50	COFFEE BREAK	Reverse Trade Show
17:50 ~ 19:30	SESSION 4 : Advanced Design and Evaluation Technology	
19:30 ~ 21:00	RECEPTION PARTY (<i>Conference Room B</i>)	

FRIDAY 16 September

	MAP (Conference Room A)	RTS (Exhibition Hall)
09:10 ~ 10:10	SESSION 5 : Asian Topics	
10:10 ~ 10:40	COFFEE BREAK	Reverse Trade Show
10:40 ~ 12:00	SESSION 6 : Automobile Design Technology	
12:00 ~ 13:30	LUNCH BREAK	Reverse Trade Show
	(Conference Room A)	(Conference Room B)
13:30 ~ 15:10	SESSION 7: Simulation and Analysis	SESSION 8: Substrate and Board
15:10 ~ 15:40	COFFEE BREAK	Reverse Trade Show
15:40 ~ 17:00	SESSION 9: Testing Technology	SESSION 10: System-in-a-Package Technology
17:00 ~ 19:00	SESSION 11: Poster Presentation and Business Meeting	

MAP&RTS 2005 PROGRAM

THURSDAY 15 September

13:00 ~ 13:15 **Opening Remark** Conference Room A

13:15 ~ 14:45 **SESSION 1: Invited Talks**

Chair: Hajime Tomokage (*Fukuoka University*)

13:15~14:00 1.1 **For the Revival of Japanese Semiconductor Industry**

Shuichi Otsuka

Hiroshima Elpida Memory, Inc. (Japan)

14:00~14:45 1.2 **Greater China's Big Leap in ICT Industry**

Colley Hwang

DigiTimes Publication Inc. (Taiwan)

14:45 ~ 15:00 **COFFEE BREAK & Reverse Trade Show**

15:00 ~ 15:40 **SESSION 2 : JEITA Program** Conference Room A

Chair : Jae-Ho Lee (*Hongik University*)

15:00~15:20 2.1 **Jisso to Create the World of Electronics and Information Technology**

Hisao Kasuga

NEC Electronics Corporation (Japan)

15:20~15:40 2.2 **Printed Wiring Board Technology Roadmap & Embedded Active Devices
Technology Trends from Jisso Technology Roadmap 2005**

Henry H. Utsunomiya

Interconnection Technologies, Inc.(Japan)

15:40 ~ 16:00 **COFFEE BREAK & Reverse Trade Show**

16:00 ~ 17:30 **SESSION 3 : Package-on-Package Technology** . . Conference Room A

Chair : Eddie Ohtsuru (*Kyushu University*)

16:00~16:20 3.1 **Toward the 3D-SiP Era**

Morihiro Kada

Sharp Corporation (Japan)

16:20~16:40 3.2 **Amkor 3D PKG Development Activity**

Jun Taniguchi

Amkor Technology Japan KK. (Japan)

16:40~17:10 3.3 **The Third Jisso Revolution "The issues and the future view of POP three
dimensional Jisso"**

Yusuke Yamamoto

Panasonic Factory Solutions Co., Ltd. (Japan)

17:10~17:30 3.4 **Characteristics of New Solder Paste for Three dimensional Package**
Yoshinori Takagi
Senju Metal Industry Co., Ltd. (Japan)

17:30 ~ 17:50 COFFEE BREAK & Reverse Trade Show
--

17:50 ~ 19:30 SESSION 4 : Advanced Design, Fabrication and Evaluation

Chair : Donghwan Kim (*Korea University*) Conference Room A

17:50~18:10 4.1 **Integration of 3D-EM Simulation and Measurement**
Eiji Tanabe
AET Japan, Inc. (Japan)

18:10~18:30 4.2 **Development of a New Confocal Video-Based Measuring System for Coordinate Measurement of 3 Dimensional Features of the State-of-Art Semiconductor Packages**
Fusao Shimizu*, Hiroo Tsumuraya*, Shuichi Sakai**
**Nikon Corporation Instruments Company (Japan)*,
** *Nikon Instech Co., Ltd. (Japan)*

18:30~18:50 4.3 **Demand for High Speed Thermal Shock Testing of Printed Circuit Board**
Shinichi Sumiyoshi
INOUEKI CO., LTD (Japan)

18:50~19:10 4.4

EPISIL (Taiwan)

19:10~19:30 4.5 **Advanced Analysis Technology Supporting SiP**
Ken Sugiura* , Hiroaki Itomine** , Hiroshi Murakami*
**FUKURYO SEMICON ENGINEERING, CORPORATION*,
***OLYMPUS CORPORATION (Japan)*

19:30 ~ 21:00 RECEPTION PARTY (<i>Conference Room B</i>)
--

FRIDAY 16 September

09:10 ~ 10:10 SESSION 5: Asian Topics Conference Room A

Chair: Toru Takahashi (*Japan External Trade Organization*)

09:10~09:30 5.1 **Challenges and Business Opportunities in Electronics Industry in Malaysia**
Afifuddin A.Kadir
Malaysian Industrial Development Authority (Malaysia)

09:30~09:50 5.2 **Opportunities for IC/Electronics Industries in HK and PRD**
S.W Cheung
Hong Kong Science and Technology Parks Corporation (China)

09:50~10:10 5.3 **Outline of Kitakyushu Science and Research Park**
Yukie Nomi

10:10 ~ 10:40 COFFEE BREAK and Reverse Trade Show

10:40 ~ 12:00 **SESSION 6: Automobile Design Technology** · · Conference Room A
Chair: Todd Takaki (Inoueki Co.,Ltd.)

10:40~11:20 6.1 **Automotive Market and Semiconductor Technology Trend**
Michio Sato
Freescale Semiconductor Japan Ltd. (Japan)

11:20~11:40 6.2 **The Future of car electronics and Testing of semiconductor devices for
Automotive**
Yasunori Yamaguchi
Teradyne, Inc. (Japan)

11:40~12:00 6.3 **Introduction of ENG CMOS Sensor Core IP**
T. Abe
Exploitation of Next Generation Co., Ltd. (Japan)

12:00 ~ 13:30 LUNCH BREAK and Reverse Trade Show

13:30 ~ 14:50 **SESSION 7: Simulation and Analysis** · · · · · Conference Room A
Chair: Seiichiro Yoshida (New Japan Radio Co.,Ltd.)

13:30~13:50 7.1 **Co-Simulation of Chip and Package for Power Integrity Optimization in
High Speed Digital System**
S. Seki
ATE Service Corp. (Japan)

13:50~14:10 7.2 **Encapsulation of Semiconductors – A Multi-physics Simulation**
Sejin Han*, Franco Costa**, Shishir Ray** and Peter K. Kennedy**
**Moldflow Corporation (U.S.A.), **Moldflow Pty. Ltd. (Australia)*

14:10~14:30 7.3 **Open DFM Visualization Technology - 3D CAD System for DFM**
Andres Carrasco*, Masayuki Kayama**
**CAD Design Software (U.S.A.),
**Nagase Electronic Equipment Service Co., Ltd., (Japan)*

14:30~14:50 7.4 **Introduction of the Thermal Design Tools from Fluent Inc.**
Kazuhiro Ogawa
Fluent Asia Pacific Co.,Ltd.,

14:50 ~ 15:40 COFFEE BREAK and Reverse Trade Show

13:30 ~ 15:10 **SESSION 8: Substrate and Board** · · · · · Conference Room B
Chair: Yangdo Kim (Pusan National University)

- 13:30~13:50 8.1 **High-Frequency Dielectric Properties of Halogen-Free Material for PWBs**
Y.Shimada and E.Watanabe
Hitachi Chemical Co.,Ltd. (Japan)
- 13:50~14:10 8.2 **New IC Package Structures for High Speed Chip to Chip Interconnections**
Joseph Fjelstad
SiliconPipe, Inc (U.S.A.)
- 14:10~14:30 8.3 **Copper Electroplating on Flexible Substrate for CoF (Chip on Fiilm) Applications**
Sung-Sup Byun, Jung-Eun Kang, Jae-Ho Lee
Hongik University (Korea)
- 14:30~14:50 8.4 **PWB Technology for Wafer Probe Cards and Burn-in Boards**
Isao Kaneda
Oki Printed Circuits Co.,Ltd. (Japan)
- 14:50~15:10 8.5
Hajime Fukawa
Minami

15:10 ~ 15:40	COFFEE BREAK and Reverse Trade Show
----------------------	--

15:40 ~ 17:00 SESSION 9: Testing Technology Conference Room A
Chair: Fumiaki Shigeoka (Ueno Seiki Co.,Ltd.)

- 15:40~16:00 9.1 **Proposal of SoC Testing -Challenges to Improving QCDS by Integration of SoC Design and Test-**
Norio Kubo
Yokogawa Electric Corporation (Japan)
- 16:00~16:20 9.2
KYEC (Taiwan)
- 16:20~16:40 9.3 **Approach of the Product Engineering Business**
Megumi Nakano
Elia Co., Ltd. (Japan)
- 16:40~17:00 9.4 **Open DFT Yield Solution**
Rocky Kobayashi
ATE Service Corp. (Japan)

15:40 ~ 17:00 SESSION 10: System-in-a-Package Technology
. Conference Room B
Chair: Henry H. Utsunomiya (Interconnection Technologies Inc.)

- 15:40~16:00 10.1 **System-in-a-package (SiP) Solution**
Mamoru Kajihara
NEC Electronics Corporation (Japan)
- 16:00~16:20 10.2 **Wafer Process Chip Size Package Consisting of Double-Bump Structure for Small-Pin-Count packages**

Kaoru Mitsuka, Hiroyuki Kurata, Jun Furukawa, Michiya Takahashi
New Japan Radio Co., Ltd. (Japan)

16:20~16:40 10.3 **Trend of WLP Technology and Next Generation Packaging
“WLP & EWLP”**

Daishi Komatsu
CASIO COMPUTER Co.,Ltd.(Japan)

16:40~17:00 10.4 **Introducing "System in Silicon" - New Multichip Technology with
Microbump**

Naoya Tohyama
System Fabrication Technologies, Inc.(Japan)

17:00 ~ 19:00 SESSION 11: Poster Presentation with wines

• • • • • • • • Exhibition Hall

Chair: Hiroshi Kido (*Kitakyushu University*)